

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZHAOHUI WU	06/12/2018
WEI KANG	06/12/2018
XIAOQUAN GUO	06/12/2018
JUN ZHANG	06/12/2018
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<b>Name:</b>	DONGGUAN CHINA ADVANCED CERAMIC TECHNOLOGY CO., LTD.
<b>Street Address:</b>	NO. 12, GULIAO 1ST RD., TANGXIA TOWN
<b>City:</b>	DONGGUAN, GUANGDONG
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	523000
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16029649
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<b>ATTORNEY DOCKET NUMBER:</b>	CFPA9517-23362
<b>NAME OF SUBMITTER:</b>	LEONG C. LEI
<b>SIGNATURE:</b>	/Leong C. Lei/
<b>DATE SIGNED:</b>	07/09/2018
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 2</b>	

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# Combined Declaration and Assignment for Patent Application

Title of the Invention: CERAMIC MODULE FOR POWER SEMICONDUCTOR

INTEGRATED PACKAGING AND PREPARATION METHOD THEREOF

As a below named inventor, I hereby declare that:

This declaration is directed to:

- ☒ The attached application, or  
☐ U.S. Application Number or PCT International Application Number \_\_\_\_\_  
 filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

## ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) CERAMIC MODULE FOR POWER SEMICONDUCTOR INTEGRATED PACKAGING AND PREPARATION METHOD THEREOF

The PATENT RIGHTS referred to in this agreement are:

(check one) ☒ a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.

☐ U.S. patent application Serial No. \_\_\_\_\_, filed \_\_\_\_\_.

☐ U.S. patent No. \_\_\_\_\_, issued \_\_\_\_\_.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one) ☒ U.S. patent rights only.

☐ worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. patent application identified above.

The ASSIGNOR(S) referred to in this agreement is (or are):

(check one) ☒ Inventor(s)

☐ Present Owner

(Full name of sole or first ASSIGNOR) Zhaohui Wu

(Address) No. 2, Guliao 2<sup>nd</sup> Road, Tangxia Town, Dongguan, Guangdong 523000, China

(Full name of second joint ASSIGNOR, if any) Wei Kang

(Address) No. 2, Guliao 2<sup>nd</sup> Road, Tangxia Town, Dongguan, Guangdong 523000, China

(Full name of third joint ASSIGNOR, if any) Xiaoquan Guo

(Address) No. 2, Guliao 2<sup>nd</sup> Road, Tangxia Town, Dongguan, Guangdong 523000, China

(Full name of fourth joint ASSIGNOR, if any) Jun Zhang

(Address) No. 2, Guliao 2<sup>nd</sup> Road, Tangxia Town, Dongguan, Guangdong 523000, China

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) Dongguan China Advanced Ceramic Technology Co., Ltd.

(Address of assignee) No. 12, Guliao 1<sup>st</sup> Road, Tangxia Town, Dongguan, Guangdong 523000, China

The ASSIGNEE is:

(check one) ☐ An Individual.

☐ A Partnership.

☒ A Corporation of China

(state or country)

The ASSIGNOR(S), in consideration of \$1.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to the ASSIGNEE; its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS; and

the right to claim priority under 35 USC 119, based on any earlier foreign applications for this invention.

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

ASSIGNOR(S) authorize(s) LEONG C. LEI (Reg. No. 50402) to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

Zhaohui Wu

Zhaohui Wu

(Signature of sole or first ASSIGNOR)

June 12, 2018

(Date)

Wei Kang

Wei Kang

(Signature of second joint ASSIGNOR)

June 12, 2018

(Date)

Xiaoquan Guo

Xiaoquan Guo

(Signature of third joint ASSIGNOR)

June 12, 2018

(Date)

Jun Zhang

Jun Zhang

(Signature of fourth joint ASSIGNOR)

June 12, 2018

(Date)